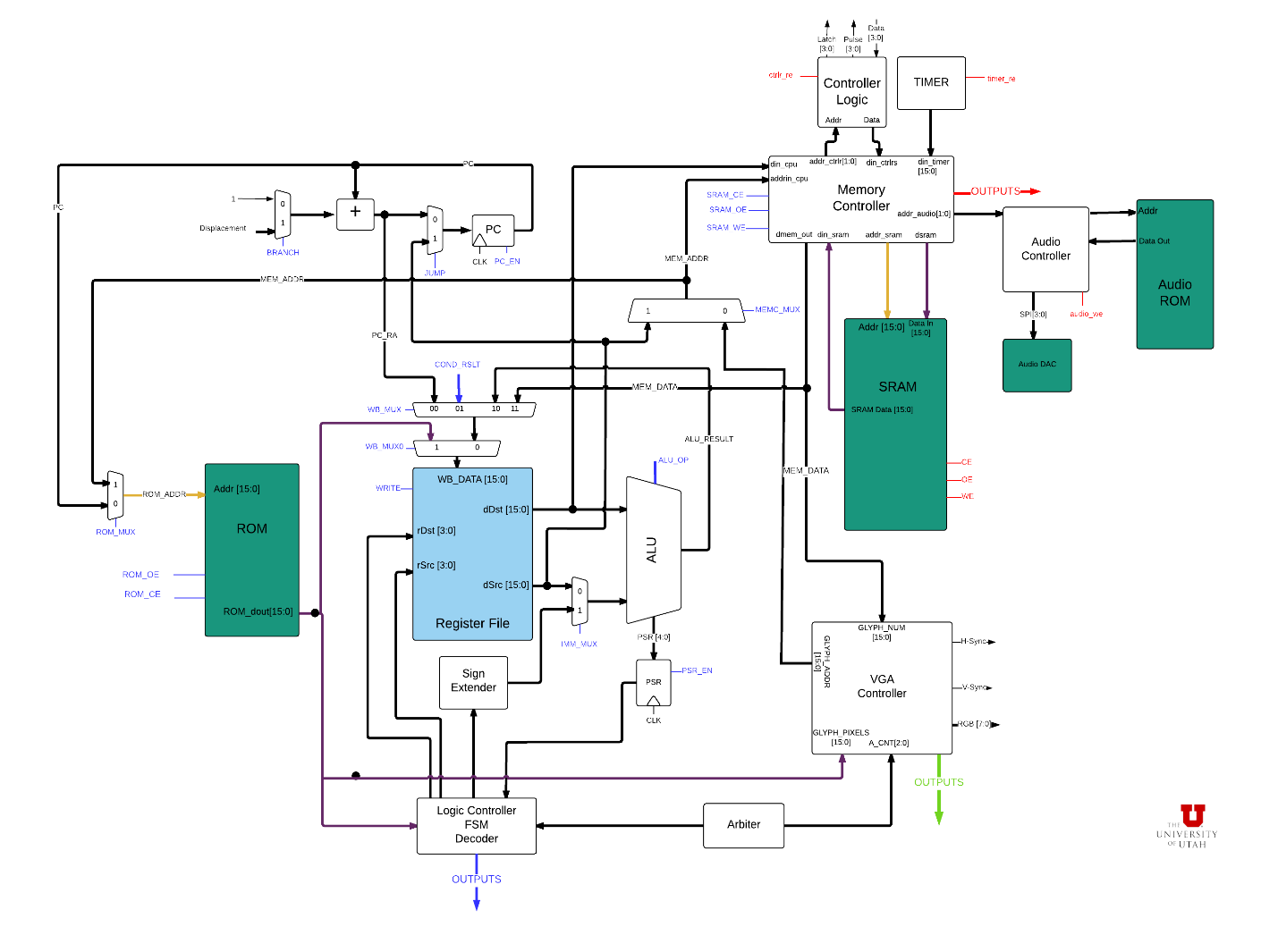
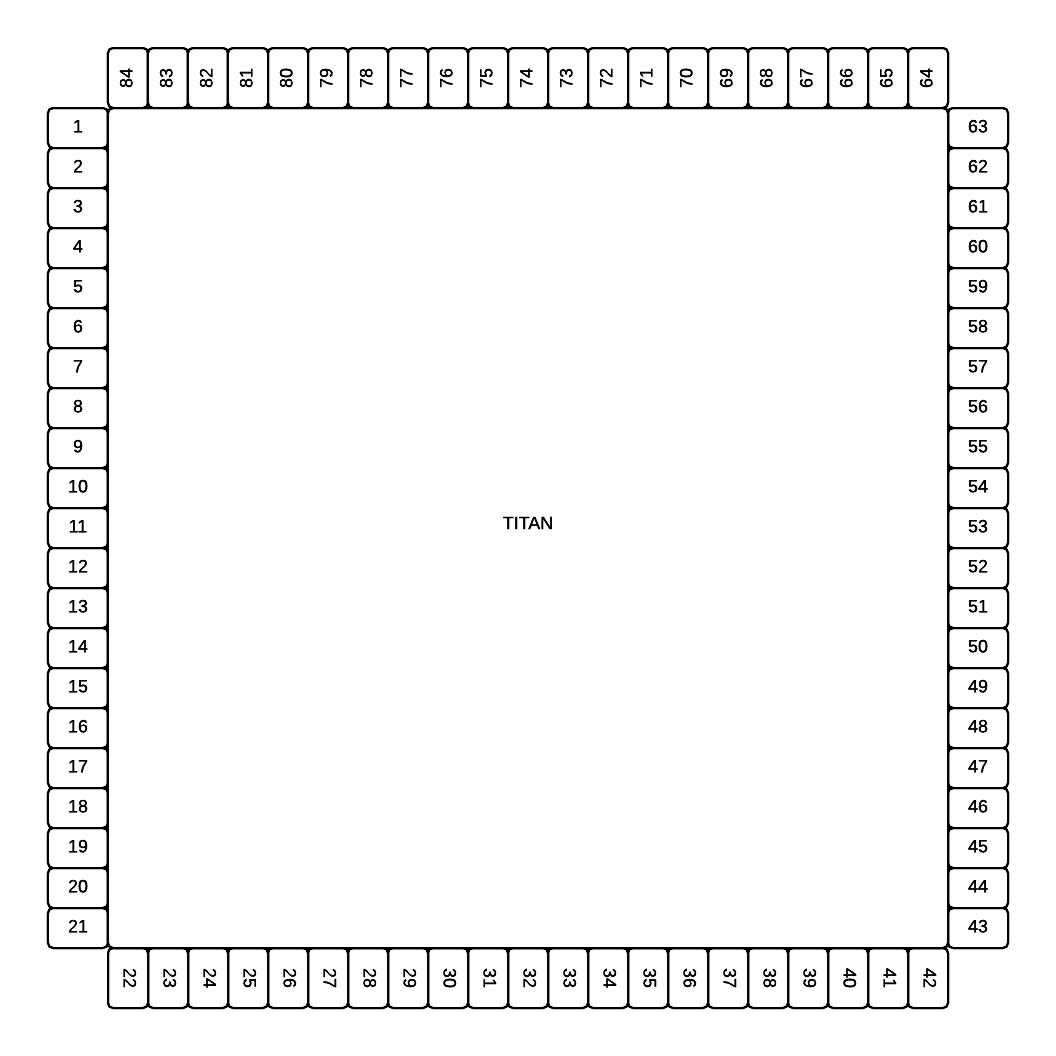
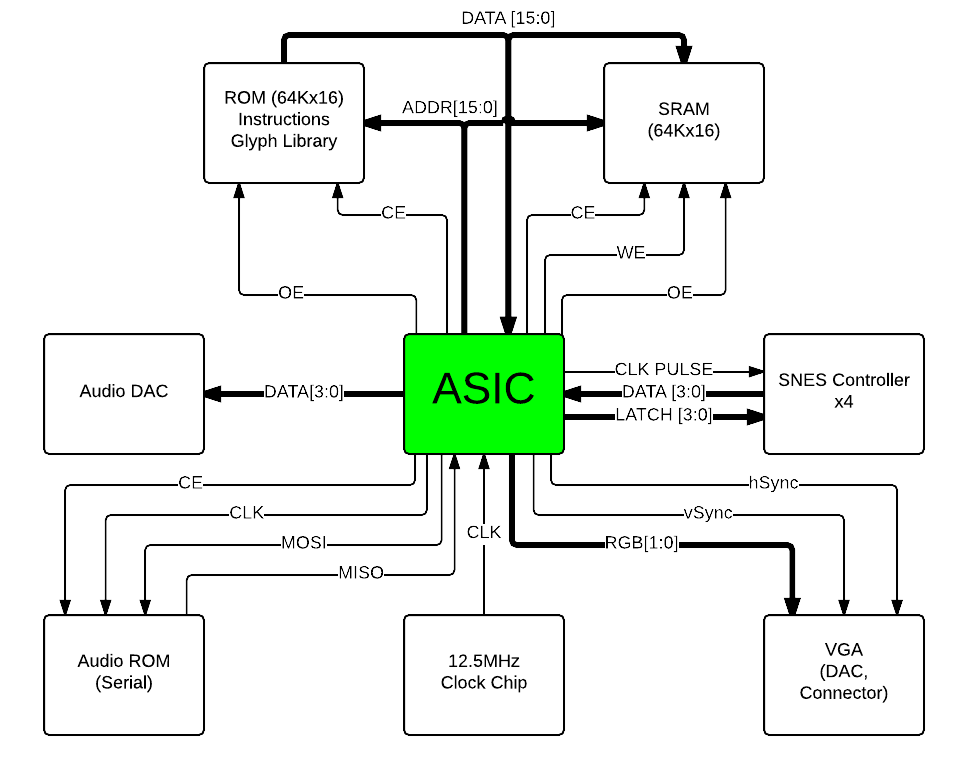
**T.E.S.S. Data Sheet**

1. **Overview**
   1. **Located in the proposal**
   2. **Talk about general overview of the chip**
2. **Features**
   1. **Mention VGA, AUDIO, external memory interface from a high level**
3. **Abbreviations**
   1. **Tabulate possible abbreviations that might be used in the paper**
4. **Block Diagram  
   **
5. **Pin Layout  
   **

**Pin Table**

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1. **Data path**
   1. **Core**
   2. **Audio**
   3. **VGA**
   4. **Memory Map**
2. **Peripheral interface**
3. **Electrical Characteristics**
4. **Application   
   **
5. **Package Dimensions   
   Available through MOSIS**